

IN THE SPECIFICATION

A. Substitute Specification

Submitted herewith is a substitute specification. In accordance with 37 C.F.R. §1.125, attached to this response is a marked-up version and a clean version of the substitute specification. The substitute specification includes no new matter.

B. Additional Amendments to Substitute Specification

The following amendments to the specification are made to the clean version of the substitute specification.

Please replace the paragraph beginning at page 7, line 1, with the following amended paragraph:

The management apparatus 720 has a management program 722 for controlling the management system; the factory-side controller 730 has an operation control program 733 for controlling the controller's operation; and the vendor-side controller 810 has an operation control program 813 for controlling the operation thereof.

Please replace the paragraphs beginning at page 7, line 22 and line 24, respectively, with the following amended paragraphs:

[Patent Publication 1] Japanese Patent Laid-Open Publication No. 2002-43290 (~~Fig. 3~~)

[Patent Publication 2] Japanese Patent Laid-Open Publication No. 2002-163016 (~~Fig. 1~~)

Please replace the paragraph beginning at page 33, line 17, with the following amended paragraph:

A data file, in which a control of a certain operation of a device corresponding to a predetermined macro file (hereinafter referred to as an “interlock”) is defined, is not in a form of source code but is concisely described by using IDs (identifiers) in a predetermined data format, e.g., EXCEL and stored in the server 103. An ID, as an instructional or conditional statement for defining an interlock of each device, is a portion corresponding to the control of a certain operation of a corresponding device in, e.g., source codes of sequential operations converted into hard codes, and, like the commands as described, is taken out of the source codes of the sequential operations. Based on such data file, an interlock for a specific operation of each device in the substrate processing apparatus 101 is defined.

Please replace the paragraph beginning at page 35, line 19, with the following amended paragraph:

In Fig. 5, the leftmost column of an Excel sheet as a data file, i.e., 「 Abstract Table」 defines an operation of a device and an ID 「 NMS_ILT_BPC_OUT_VLV2」 represents an operation of opening the BPC OUT valve (G82). The next column 「 Check Item」 describes conditions that need to be satisfied in order to execute such operation of the device, i.e., interlock, wherein an ID 「 BPC OUT valve (G82) open interlock, the presence of wafer + ESC HV OFF, NMF_ILF_ESC_HV_OFF_WAHER, the presence of wafer + ESC VOLTAGE ZERO, NMSMNS_ILF_ESC_VOLT_ZERO_WAHER」 specifies conditions that a

semiconductor wafer W is placed on a lower electrode while a high frequency power supply is turned off; or the semiconductor wafer W is placed on the lower electrode while a current generated by a voltage applied from the high frequency power supply is 0.

Please replace the paragraph beginning at page 60, line 21, with the following amended paragraph:

Though the embodiments have ~~has~~ been described for the case where an etching process is exemplified as a substrate processing conducted by the substrate processing system 100 and the substrate processing system 600, the substrate processing executed by the substrate processing system 100 and the substrate processing system 600 is not limited to the etching process but can be, e.g., a CVD process, an ashing process, an ion doping process, a sputtering process, and the like.

Please replace the paragraphs in the Abstract with the following amended paragraphs:

~~[Purpose] The present invention provides a system and method for processing a substrate while reducing the number of works that should be done by a software engineer; and a program for performing the method.~~

~~[Constitution]~~ A substrate processing system allows to reduce the number of works that should be done by a software engineer. The system 100 includes a substrate processing apparatus 101; a substrate processing controller 102 for controlling the substrate processing apparatus 101; and a server 103 for storing therein commands, i.e., instructional statements, for defining an operation of each device. The substrate processing controller 102 has a RAM 105 serving as a work

space for creating a macro file corresponding to each of processes divided from the whole substrate processing or for changing the content of a macro file; and an executor 108 composed of, e.g., CPU for executing a process sequence macro obtained by a combination of the created macro files. The user creates a macro file describing a sequential operation of each process or changes the content of a macro file by arranging the stored commands.

~~{Selected drawing}~~ Figure 4

Attachment:

Marked-up version of the amended specification.

Clean version of the amended specification.